

XPand3200 Series

End of Life

Sub-½ ATR, Conduction-Cooled System Supporting Conduction-Cooled Modules

Please contact X-ES Sales

- ▶ ½ ATR-compliant, conduction-cooled chassis (reduced height and length)
- ▶ Physical dimensions of 8.75 in. (L) x 4.88 in. (W) x 5.62 in. (H)
- ▶ 3U VPX and cPCI backplanes available
- ▶ Five conduction-cooled 3U VPX or 3U CompactPCI slots and one power supply slot
- ▶ Configurable front panel I/O connectors
- ▶ SATA SSD memory module with easy removal and insertion (optional)
- ▶ Select from an extensive lineup of X-ES designed and manufactured SBC, FPGA, and I/O modules
- ▶ Integration services with third-party modules available
- ▶ Up to 200 W from a MIL-STD-704 28 VDC or 115 VAC source
- ▶ MIL-STD-461 E/F EMI filtering
- ▶ Environmentally sealed
- ▶ Internal holdup of up to 60 ms at 200 W



XPand3200 Series

The XPand3200 Series redefines the limits of power, performance, and functionality in a sub-½ ATR chassis. XPand3200 Series systems are based on a conduction-cooled, fully ruggedized chassis designed to meet the rigorous standards of MIL-STD-810 while integrating the latest power-saving and performance-enhancing technology. In today's avionics and ruggedized environments, size really does matter, and the XPand3200 sets a new standard for sub-½ ATR computing.

Depending on your processing requirements, XPand3200 Series systems can be populated with high-performance, low-power 3U VPX or cPCI modules designed and manufactured by X-ES. X-ES also has an extensive lineup of XMC and PMC solutions to fulfill your data-processing and I/O requirements. Additionally, X-ES provides integration services for third-party modules.

An optional SATA SSD memory module provides the convenience of removable storage and the ruggedness of solid-state memory at up to 64 GB. An optional front-panel USB port provides system monitoring and maintenance capabilities. X-ES maximizes power supply performance, supporting up to 200 W from a MIL-STD-704 28 VDC or 115 VAC input. Internal EMI filtering and hold-up for up to 60 ms at 200 W are also provided.

X-ES

Extreme Engineering Solutions

*“Fast, Flexible, Customer-Focused
Embedded Solutions”*

Extreme Engineering Solutions

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Physical Characteristics

- ½ ATR-compliant, conduction-cooled chassis (reduced height and length)
- Dimensions: 8.75 in. (L) x 4.88 in. (W) x 5.62 in. (H)

Backplane Options

- 3U VPX
- 3U cPCI
- Custom backplane solutions available

Front Panel I/O Options

- USB 2.0- and 1.0-compliant interface
- Three user-defined push buttons
- Removable SATA SSD storage media bay with high-reliability connector
- Custom front panel I/O

Back Panel I/O Options

- Up to three D38999 circular connectors for I/O
- DVI graphics interfaces
- USB 2.0- and 1.0-compliant interfaces
- 10/100/1000BASE-T Gigabit Ethernet interfaces
- RS-232/422 serial links
- MIL-STD-1553
- ARINC-429
- Custom I/O via XMC/PMC modules
- Custom I/O via third-party modules

Power Supply Options

- MIL-STD-704 28 VDC input voltage support (default)
- MIL-STD-704 115 VAC input voltage support
- Up to 60 ms internal hold-up time at 200 W
- Up to 110 ms internal hold-up time at 120 W
- Additional power supply options available

